

# CP Series 導熱絕緣帽套 Thermal Cap



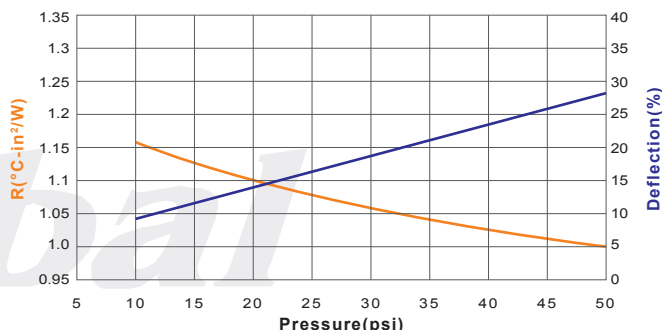
## 產品特性 Features

Low thermal contact resistance 低熱阻抗  
Electrically isolating 高絕緣性  
Decrease the weight of the product 降低產品重量  
Easy to assemble 簡易安裝組件  
Thermal conduction and buffer effect 熱傳導與緩衝效果

## 產品應用端 Applications

Electronic components: IC, CPU, MOS  
LED, M/B, P/S, Heat Sink,  
LCD-TV, Notebook PC, PC, Telecom Device, Wireless Hub.....etc  
DDR II Module, DVD Applications, Hand-set applications.....etc

## 熱阻抗VS.壓力VS.變形量示意圖 Thermal Resistance VS. Pressure VS. Deflection

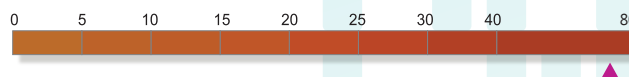


Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	1.16	9
20	1.1	14
50	1	28

## 選擇尺寸 Standard Sizes (mm)

1. CP22 TO-220: 11.4 x 16 x 5.8
2. CP23 TO-220: 11.4 x 21.5 x 5.8
3. CP33 TO-247: 17.5 x 28.5 x 5.8

Hardness 軟硬度 : 75 (Shore A)



Testing sample thickness: 0.45mm

In "Thermal resistance VS. Pressure VS. Deflection" chart, CP Series provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower. CP Series provides good compliance and softness.

Properties	CP22/CP23/CP33	Unit	Tolerance	Test Method
Thermal Conductivity 導熱係數	1.9	W / mK	±0.19	ASTM D5470
Thickness 厚度	0.3/0.45	mm	-	-
Color 顏色	Gray 灰	-	-	Visual 目視
Material 物質	Silicone	-	-	-
Op. Temp. range 工作溫度	-45 to 180	°C	-	-
Density 密度	2.55	g / cm³	-	ASTM D792
Breakdown Voltage AC 耐電壓值	4/6	KV	±0.4/±0.6	ASTM D149
Breakdown Voltage DC 耐電壓值	6/8	KV	±0.6/±0.8	ASTM D149
Dielectric Constant 介電係數	5.8	1000Hz	-	ASTM D150
Thermal Impedance 熱阻抗	-	°Cin² / W	-	-
t=0.3mm	10psi	1.16	°Cin² / W	ASTM D5470
	20psi	1.1	°Cin² / W	ASTM D5470
	50psi	1	°Cin² / W	ASTM D5470
TML 全部重量損失比	<0.2	%	-	ASTM E595
Hardness 硬度	75	Shore A	±7	ASTM E595